



BSI Standards Publication

Semiconductor devices — Mechanical and climatic test methods

Part 40: Board level drop test method
using a strain gauge

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National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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English version

**Semiconductor devices -
Mechanical and climatic test methods -
Part 40: Board level drop test method using a strain gauge
(IEC 60749-40:2011)**

Dispositifs à semiconducteurs -
Méthodes d'essais mécaniques et
climatiques -
Partie 40: Méthode d'essai de chute au
niveau de la carte avec utilisation d'une
jauge de contrainte
(CEI 60749-40:2011)

Halbleiterbauelemente -
Mechanische und klimatische
Prüfverfahren -
Teil 40: Prüfverfahren zum Fall einer
Leiterplatte unter Verwendung von
Dehnungsmessstreifen
(IEC 60749-40:2011)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
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Foreword

The text of document 47/2094/FDIS, future edition 1 of IEC 60749-40, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-40 on 2011-08-17.

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The following dates were fixed:

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|--|-------|------------|
| – latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement | (dop) | 2012-05-17 |
| – latest date by which the national standards conflicting with the EN have to be withdrawn | (dow) | 2014-08-17 |

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-40:2011 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-37	-	Semiconductor devices - Mechanical and climatic test methods - Part 37: Board level drop test method using an accelerometer	EN 60749-37	-

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SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 40: Board level drop test method using a strain gauge

1 Scope

This part of IEC 60749 is intended to evaluate and compare drop performance of a surface mount semiconductor device for handheld electronic product applications in an accelerated test environment, where excessive flexure of a circuit board causes product failure. The purpose is to standardize test methodology to provide a reproducible assessment of the drop test performance of a surface mounted semiconductor devices while duplicating the failure modes normally observed during product level test.

This international standard uses a strain gauge to measure the strain and strain rate of a board in the vicinity of a component. Test method IEC 60749-37 uses an accelerometer to measure the mechanical shock duration and magnitude applied which is proportional to the stress on a given component mounted on a standard board. The detailed specification shall state which test method is to be used.

NOTE 1 Although this test can evaluate a structure where the mounting method and its conditions, the design of a printed wired board, solder material, the mounting capability of a semiconductor device, etc. are combined, it does not solely evaluate the mounting capability of a semiconductor device.

NOTE 2 The result of this test is strongly influenced by the differences between soldering conditions, the design of the land pattern of a printed wired board, solder material, etc. Therefore, in carrying out this test, it is necessary to recognize that this test cannot intrinsically guarantee the reliability of the solder joint of the semiconductor devices.

NOTE 3 When the mechanical stress which is generated by this test does not occur in the actual application of the device, implementation of this test is unnecessary.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60749-37, *Semiconductor devices – Mechanical and climatic test methods – Part 37: Board level drop test method using an accelerometer*

3 Terms and definitions

For purposes of this document, the following terms and definitions apply.

3.1

device

single electronic component to be surface mounted

3.2

drop impact strength

strength of the test substrate held by a jig that is dropped from a defined height, as represented by the number of cyclic drops that finally cause fracture on the joint between a device and a PWB copper land